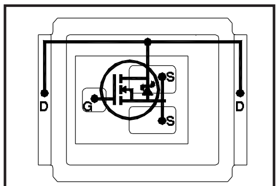
IRF6775MTRPbF

Key Parameters		
V_{DS}	150	V
$R_{DS(on)}$ typ. @ V_{GS} = 10V	47	mΩ
Q_g typ.	25.0	nC
$R_{G(int)}$ max.	3.0	Ω

Features

- Latest MOSFET Silicon technology
- Key parameters optimized for Class-D audio amplifier applications
- Low $R_{DS(on)}$ for improved efficiency
- Low Q_g for better THD and improved efficiency
- Low Q_{rr} for better THD and lower EMI
- Low package stray inductance for reduced ringing and lower EMI
- Can deliver up to 250W per channel into 4Ω Load in Half-Bridge Configuration Amplifier
- Dual sided cooling compatible
- Compatible with existing surface mount technologies
- RoHS compliant containing no lead or bromide
- Lead-Free (Qualified up to 260°C Reflow)



MZ

DirectFET™ ISOMETRIC

Applicable DirectFET Outline and Substrate Outline (see p. 6, 7 for details)

SQ	SX	ST	SH	MQ	MX	MT	MN	MZ		

Description

This Digital Audio MOSFET is specifically designed for Class-D audio amplifier applications. This MOSFET utilizes the latest processing techniques to achieve low on-resistance per silicon area. Furthermore, gate charge, body-diode reverse recovery and internal gate resistance are optimized to improve key Class-D audio amplifier performance factors such as efficiency, THD, and EMI.

The IRF6775MPbF device utilizes DirectFET™ packaging technology. DirectFET™ packaging technology offers lower parasitic inductance and resistance when compared to conventional wirebonded SOIC packaging. Lower inductance improves EMI performance by reducing the voltage ringing that accompanies fast current transients. The DirectFET™ package is compatible with existing layout geometries used in power applications, PCB assembly equipment and vapor phase, infra-red or convection soldering techniques, when application note AN-1035 is followed regarding the manufacturing method and processes. The DirectFET™ package also allows dual sided cooling to maximize thermal transfer in power systems, improving thermal resistance and power dissipation. These features combine to make this MOSFET a highly efficient, robust and reliable device for Class-D audio amplifier applications.

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{DS}	Drain-to-Source Voltage	150	V
V_{GS}	Gate-to-Source Voltage	± 20	
I_D @ T_C = 25°C	Continuous Drain Current, V_{GS} @ 10V	28	A
I_D @ T_A = 25°C	Continuous Drain Current, V_{GS} @ 10V	4.9	
I_D @ T_A = 70°C	Continuous Drain Current, V_{GS} @ 10V	3.9	
I_{DM}	Pulsed Drain Current ①	39	
P_D @T_C = 25°C	Maximum Power Dissipation	89	W
P_D @T_A = 25°C	Power Dissipation ③	2.8	
P_D @T_A = 70°C	Power Dissipation ③	1.8	
E_{AS}	Single Pulse Avalanche Energy②	33	mJ
I_{AR}	Avalanche Current ①	5.6	A
	Linear Derating Factor ③	0.022	W/°C
T_J T_{STG}	Operating Junction and Storage Temperature Range	-40 to + 150	°C

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ③⑨	——	45	°C/W
$R_{\theta JA}$	Junction-to-Ambient ⑥⑨	12.5	——	
$R_{\theta JA}$	Junction-to-Ambient ⑦⑨	20	——	
$R_{\theta JC}$	Junction-to-Case ⑧⑨	——	1.4	
$R_{\theta J\text{-}PCB}$	Junction-to-PCB Mounted	1.4	——	

Notes ① through ⑨ are on page 2

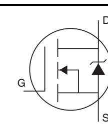
Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	150	–––	–––	V	V_{GS} = 0V, I_D = 250μA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	–––	0.17	–––	V/°C	Reference to 25°C, I_D = 1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	–––	47	56	mΩ	V_{GS} = 10V, I_D = 5.6A ④
$V_{GS(th)}$	Gate Threshold Voltage	3.0	–––	5.0	V	V_{DS} = V_{GS}, I_D = 100μA
I_{DSS}	Drain-to-Source Leakage Current	–––	–––	20	μA	V_{DS} = 150V, V_{GS} = 0V
		–––	–––	250		V_{DS} = 120V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Forward Leakage	–––	–––	100	nA	V_{GS} = 20V
	Gate-to-Source Reverse Leakage	–––	–––	-100		V_{GS} = -20V
$R_{G(int)}$	Internal Gate Resistance	–––	–––	3.0	Ω	

Dynamic @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
gfs	Forward Transconductance	11	–––	–––	S	V_{DS} = 50V, I_D = 5.6A
Q_g	Total Gate Charge	–––	25	36	nC	V_{DS} = 75V
Q_{gs1}	Pre-Vth Gate-to-Source Charge	–––	5.8	–––		V_{GS} = 10V
Q_{gs2}	Post-Vth Gate-to-Source Charge	–––	1.4	–––		I_D = 5.6A
Q_{gd}	Gate-to-Drain Charge	–––	6.6	–––		See Fig. 6 and 17
Q_{godr}	Gate Charge Overdrive	–––	11	–––		
Q_{sw}	Switch Charge (Q_{gs2} + Q_{gd})	–––	8.0	–––		
$t_{d(on)}$	Turn-On Delay Time	–––	5.9	–––	ns	V_{DD} = 75V
t_r	Rise Time	–––	7.8	–––		I_D = 5.6A
$t_{d(off)}$	Turn-Off Delay Time	–––	5.8	–––		R_G = 6.0Ω
t_f	Fall Time	–––	15	–––		V_{GS} = 10V ④
C_{iss}	Input Capacitance	–––	1411	–––	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	–––	193	–––		V_{DS} = 25V
C_{rss}	Reverse Transfer Capacitance	–––	40	–––		f = 1.0MHz
C_{oss}	Output Capacitance	–––	1557	–––		V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz
C_{oss}	Output Capacitance	–––	93	–––		V_{GS} = 0V, V_{DS} = 120V, f = 1.0MHz
C_{oss} eff.	Effective Output Capacitance	–––	175	–––		V_{GS} = 0V, V_{DS} = 0V to 120V ⑤

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	–––	–––	28	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	–––	–––	39		
V_{SD}	Diode Forward Voltage	–––	–––	1.3	V	T_J = 25°C, I_S = 5.6A, V_{GS} = 0V ④
t_{rr}	Reverse Recovery Time	–––	62	–––	ns	T_J = 25°C, I_F = 5.6A, V_{DD} = 25V
Q_{rr}	Reverse Recovery Charge	–––	164	–––	nC	di/dt = 100A/μs ④

Notes:

① Repetitive rating; pulse width limited by max. junction temperature.

② Starting T_J = 25°C, L = 0.53mH, R_G = 25Ω, I_{AS} = 11.2A.

③ Surface mounted on 1 in. square Cu board.

④ Pulse width ≤ 400μs; duty cycle ≤ 2%.

⑤ C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.

⑥ Used double sided cooling , mounting pad with large heatsink.

⑦ Mounted on minimum footprint full size board with metalized back and with small clip heatsink.

⑧ T_C measured with thermal couple mounted to top (Drain) of part.

⑨ R_θ is measured at T_J of approximately 90°C.

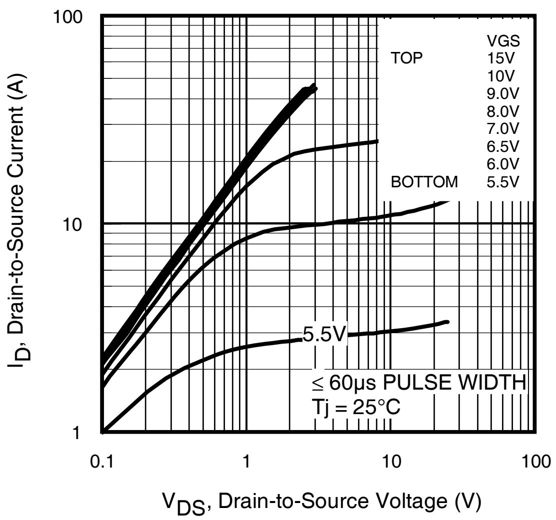


Fig 1. Typical Output Characteristics

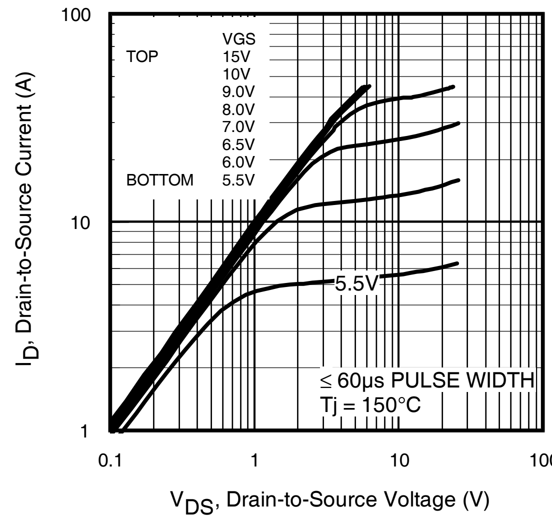


Fig 2. Typical Output Characteristics

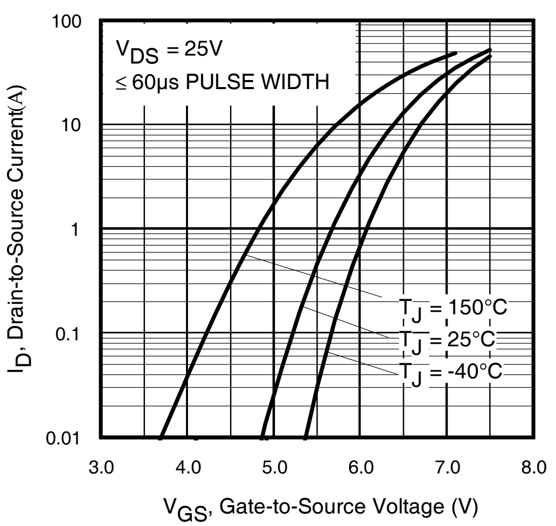


Fig 3. Typical Transfer Characteristics

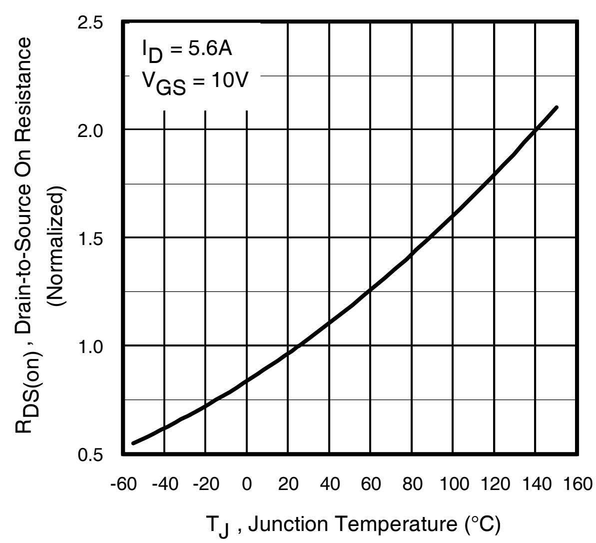


Fig 4. Normalized On-Resistance vs. Temperature

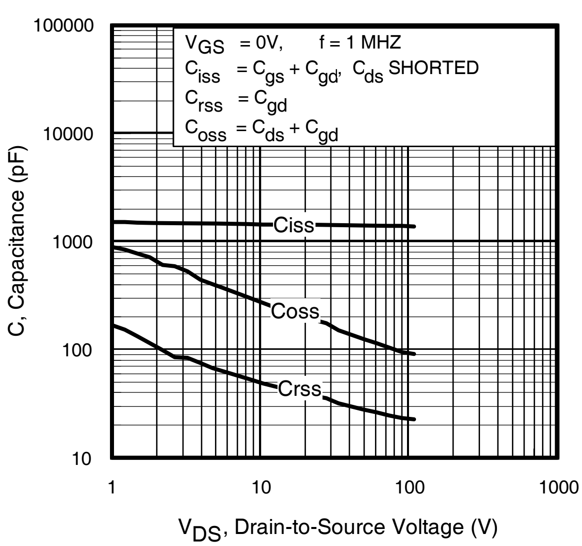


Fig 5. Typical Capacitance vs.Drain-to-Source Voltage

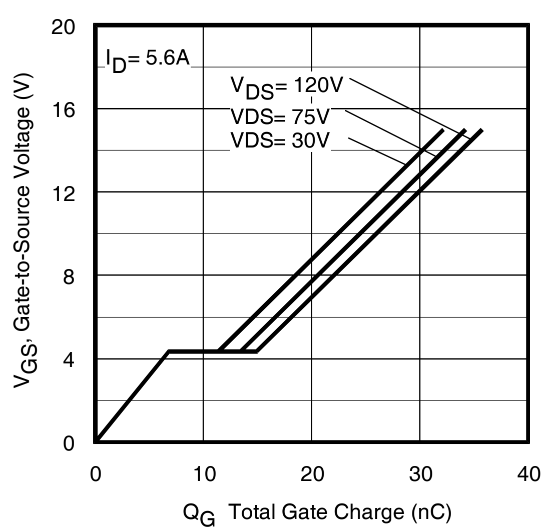


Fig 6. Typical Gate Charge vs.Gate-to-Source Voltage

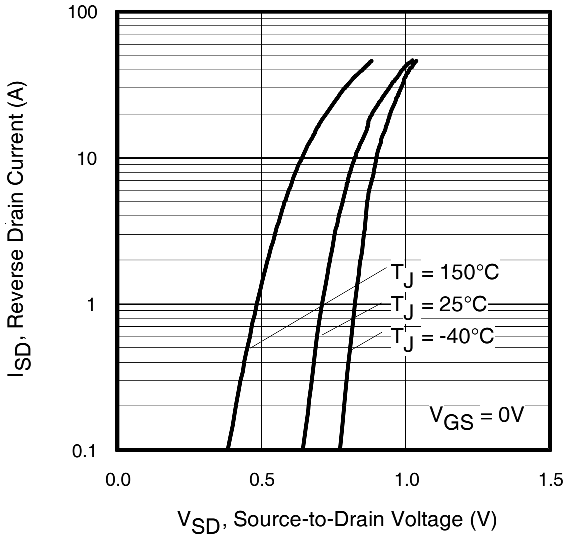


Fig 7. Typical Source-Drain Diode Forward Voltage

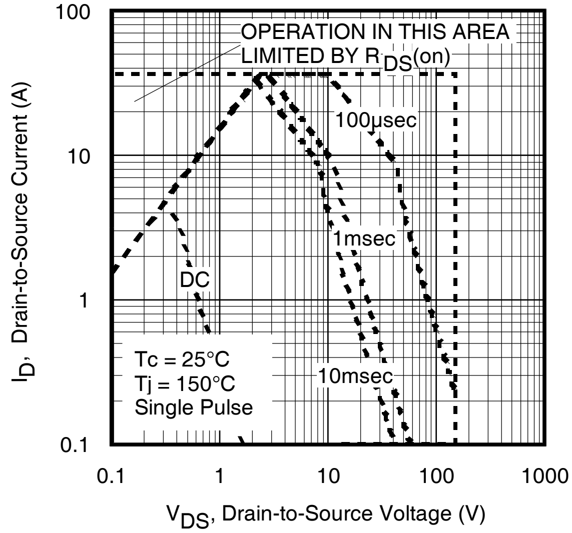


Fig 8. Maximum Safe Operating Area

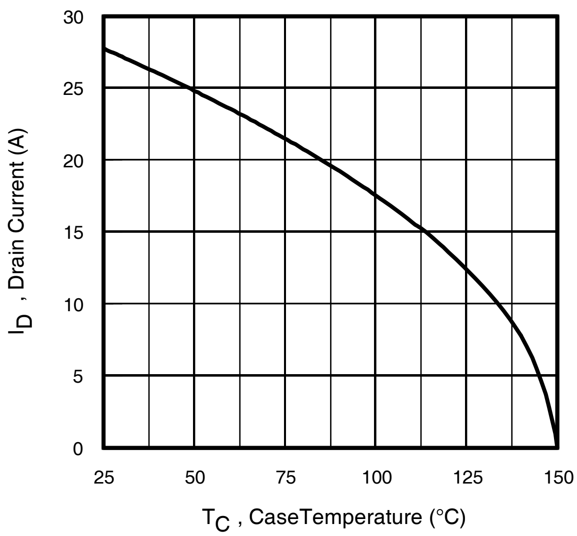


Fig 9. Maximum Drain Current vs. Case Temperature

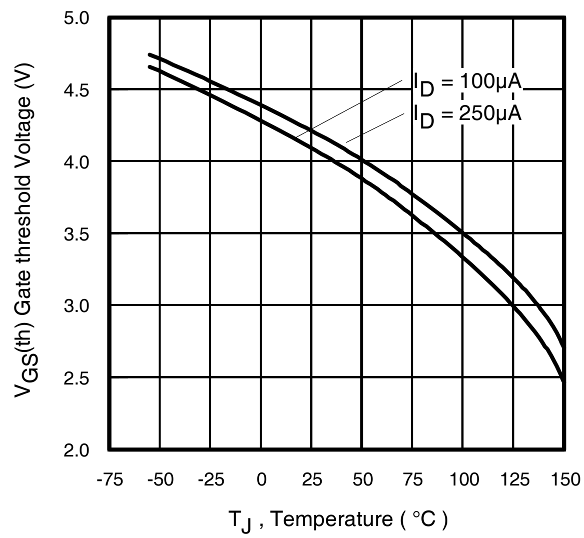


Fig 10. Threshold Voltage vs. Temperature

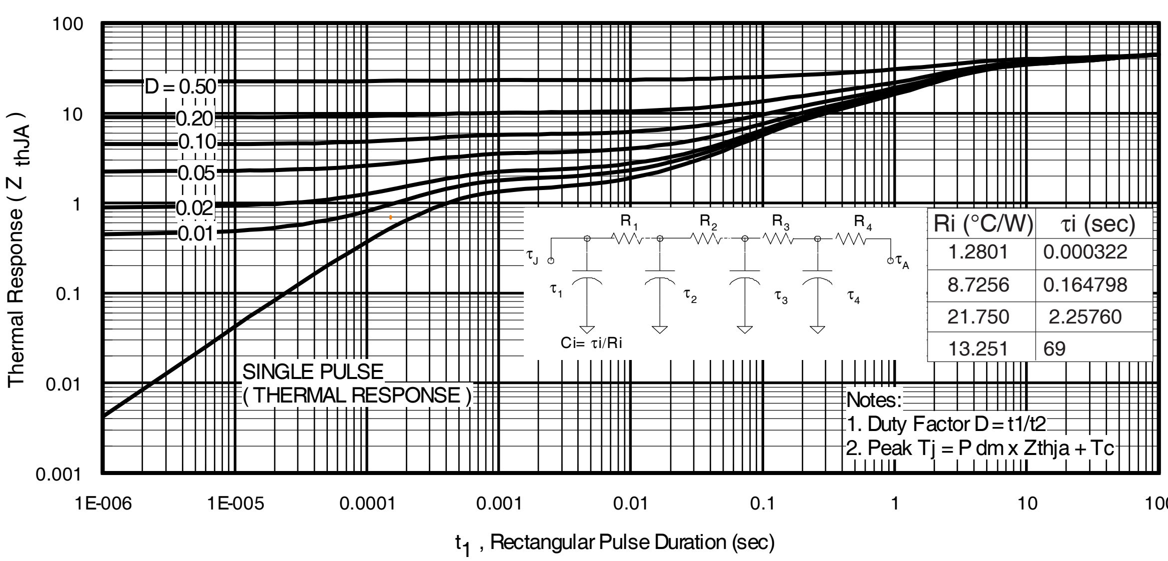


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient ③

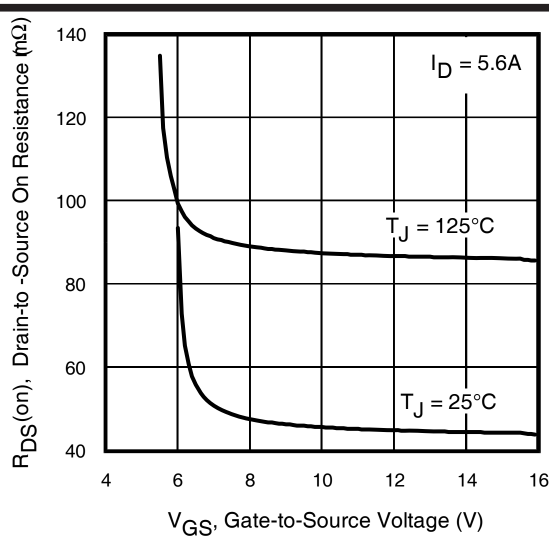


Fig 12. On-Resistance vs. Gate Voltage

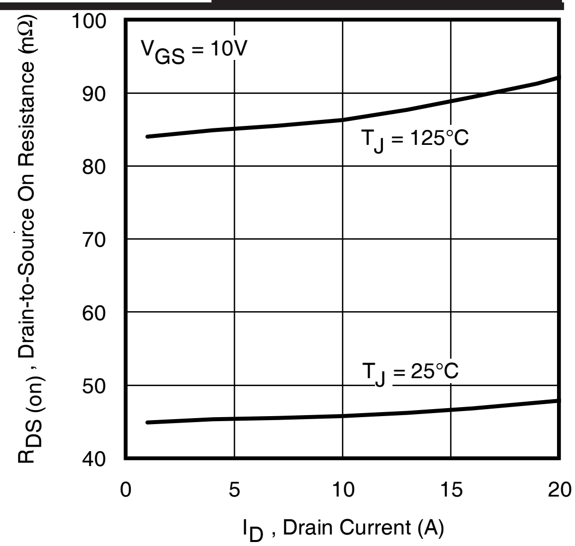


Fig 13. On-Resistance vs. Drain Current

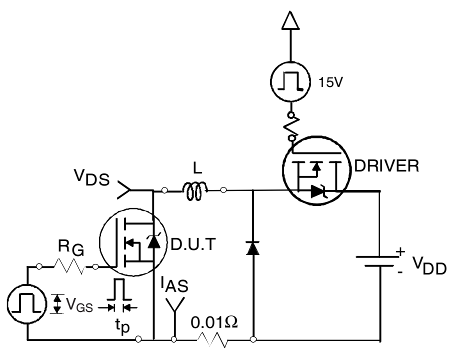


Fig 15a. Unclamped Inductive Test Circuit

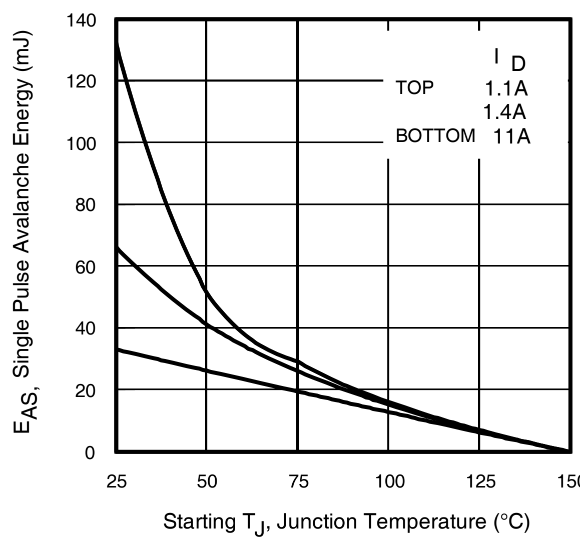


Fig 14. Maximum Avalanche Energy vs. Drain Current

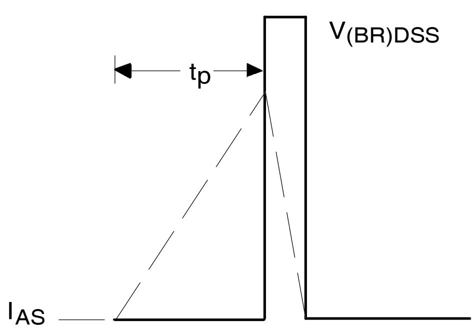


Fig 15b. Unclamped Inductive Waveforms

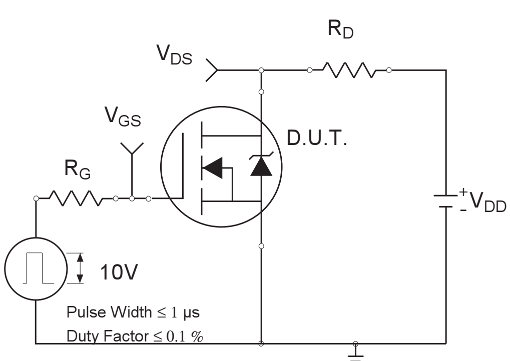


Fig 16a. Switching Time Test Circuit

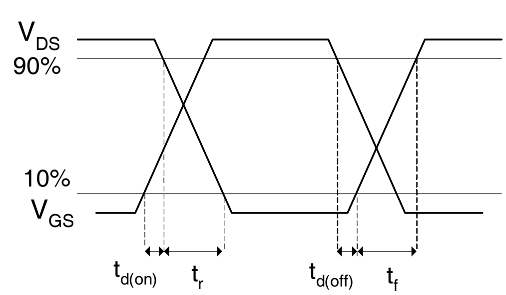


Fig 16b. Switching Time Waveforms

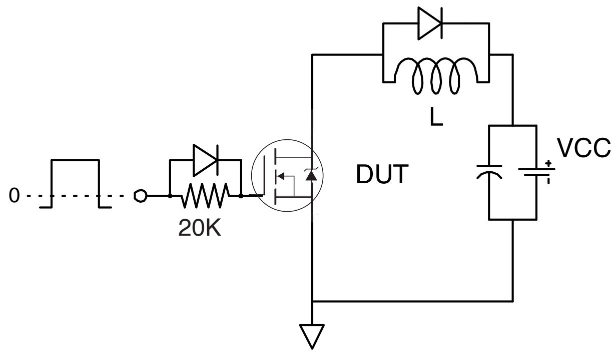


Fig 17a. Gate Charge Test Circuit

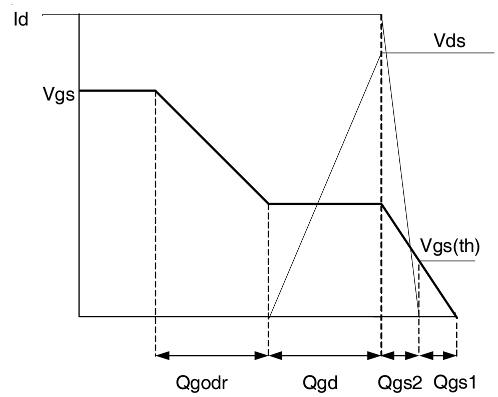
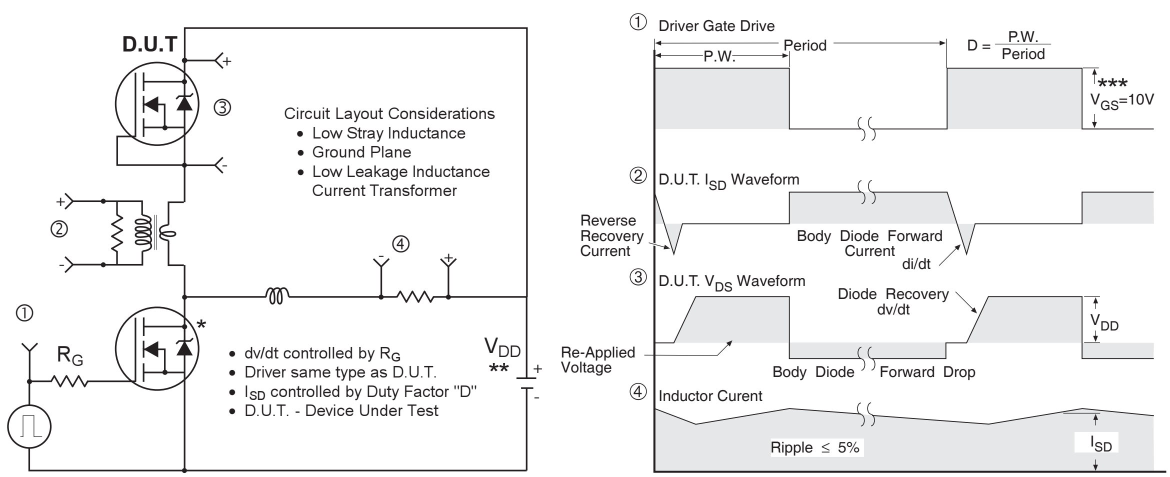


Fig 17b. Gate Charge Waveform



* Use P-Channel Driver for P-Channel Measurements

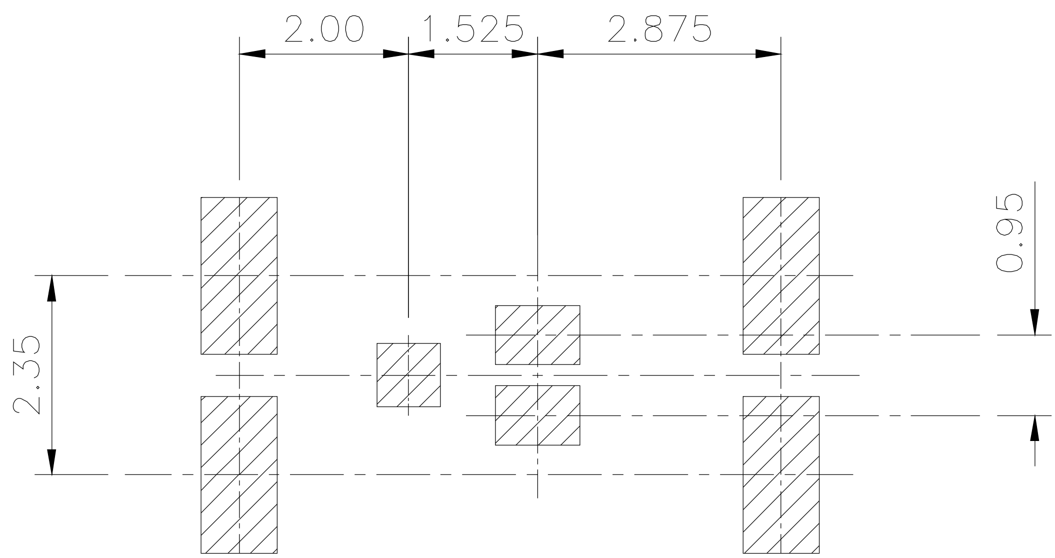
** Reverse Polarity for P-Channel

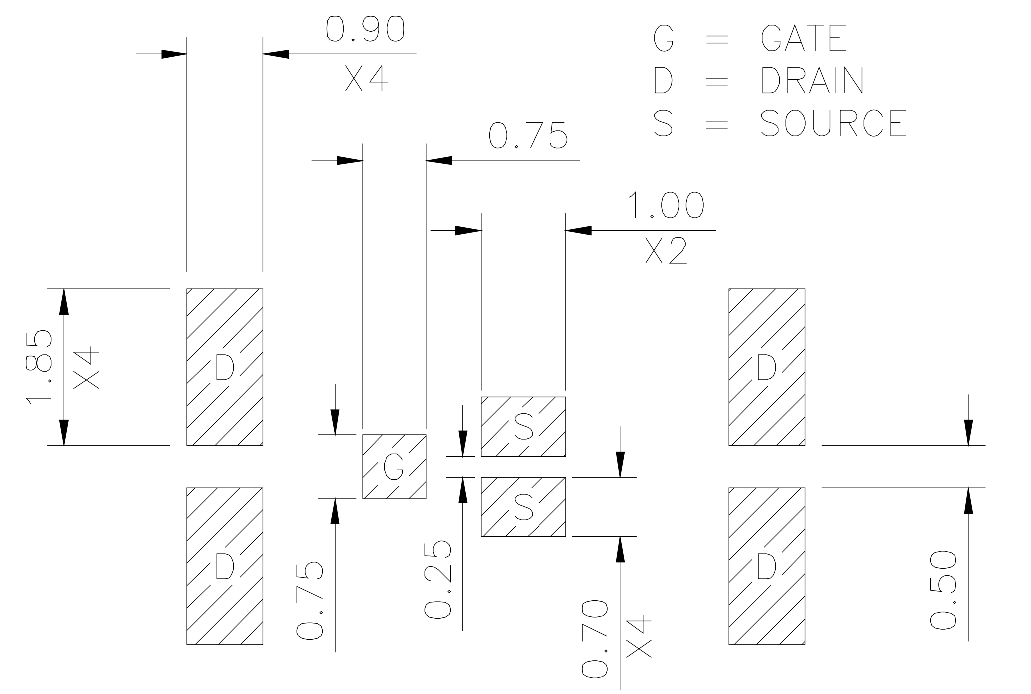
*** V_{GS} = 5V for Logic Level Devices

Fig 18. Diode Reverse Recovery Test Circuit for HEXFET® Power MOSFETs

DirectFET™ Substrate and PCB Layout, MZ Outline (Medium Size Can, Z-Designation).

Please see DirectFET application note AN-1035 for all details regarding PCB assembly using DirectFET. This includes all recommendations for stencil and substrate designs.

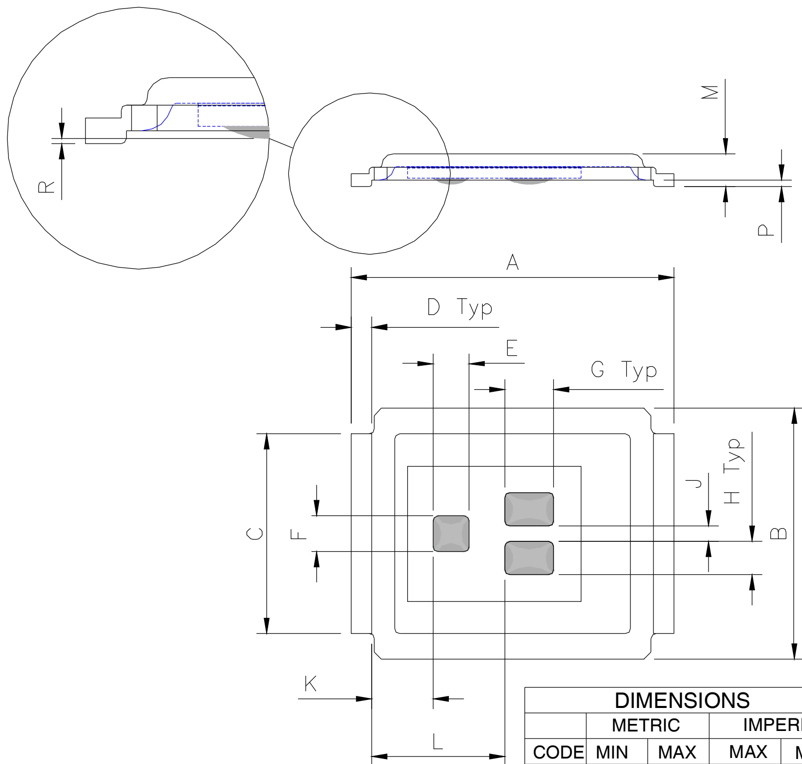




Note: For the most current drawing please refer to IR website at: http://www.irf.com/package/

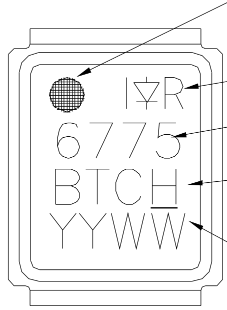
DirectFET™ Outline Dimension, MZ Outline (Medium Size Can, Z-Designation).

Please see DirectFET application note AN-1035 for all details regarding PCB assembly using DirectFET. This includes all recommendations for stencil and substrate designs.



DIMENSIONS				
	METRIC		IMPERIAL	
CODE	MIN	MAX	MAX	MAX
A	6.25	6.35	0.246	0.250
B	4.80	5.05	0.189	0.201
C	3.85	3.95	0.152	0.156
D	0.35	0.45	0.014	0.018
E	0.68	0.72	0.027	0.028
F	0.68	0.72	0.027	0.028
G	0.93	0.97	0.037	0.038
H	0.63	0.67	0.025	0.026
J	0.28	0.32	0.011	0.013
K	1.13	1.26	0.044	0.050
L	2.53	2.66	0.100	0.105
M	0.616	0.676	0.0235	0.0274
R	0.020	0.080	0.0008	0.0031
P	0.08	0.17	0.003	0.007

DirectFET™



GATE MARKING

LOGO

PART NUMBER

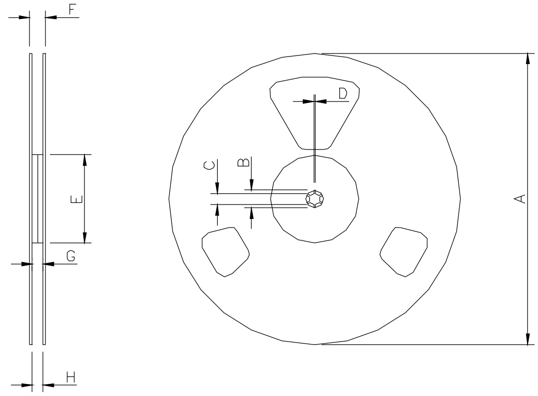
BATCH NUMBER

DATE CODE

Line above the last character of the date code indicates "Lead-Free"

Note: For the most current drawing please refer to IR website at: http://www.irf.com/package/

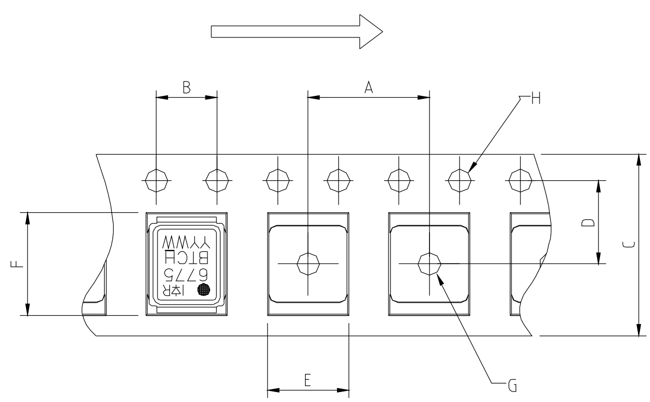
DirectFET™ Tape & Reel Dimension (Showing component orientation).



NOTE: Controlling dimensions in mm
Std reel quantity is 4800 parts. (ordered as IRF6775TRPBF). For 1000 parts on 7" reel, order IRF6775TR1PBF

REEL DIMENSIONS								
	STANDARD OPTION **(QTY 4800)**				TR1 OPTION **(QTY 1000)**			
	METRIC		IMPERIAL		METRIC		IMPERIAL	
CODE	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
A	330.0	N.C	12.992	N.C	177.77	N.C	6.9	N.C
B	20.2	N.C	0.795	N.C	19.06	N.C	0.75	N.C
C	12.8	13.2	0.504	0.520	13.5	12.8	0.53	0.50
D	1.5	N.C	0.059	N.C	1.5	N.C	0.059	N.C
E	100.0	N.C	3.937	N.C	58.72	N.C	2.31	N.C
F	N.C	18.4	N.C	0.724	N.C	13.50	N.C	0.53
G	12.4	14.4	0.488	0.567	11.9	12.01	0.47	N.C
H	11.9	15.4	0.469	0.606	11.9	12.01	0.47	N.C

LOADED TAPE FEED DIRECTION



NOTE: CONTROLLING DIMENSIONS IN MM

DIMENSIONS				
	METRIC		IMPERIAL	
CODE	MIN	MAX	MIN	MAX
A	7.90	8.10	0.311	0.319
B	3.90	4.10	0.154	0.161
C	11.90	12.30	0.469	0.484
D	5.45	5.55	0.215	0.219
E	5.10	5.30	0.201	0.209
F	6.50	6.70	0.256	0.264
G	1.50	N.C	0.059	N.C
H	1.50	1.60	0.059	0.063

Note: For the most current drawing please refer to IR website at: http://www.irf.com/package/

Revision History

Date	Comments
2/26/2014	• Updated SOA curve figure 8 to extend x axis to 150V because this device is 150V, on page 4. • Updated datasheet with new IR corporate template.

Data and specifications subject to change without notice.
This product has been designed and qualified for the Consumer market.
Qualification Standards can be found on IR's Web site.

International Rectifier

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To contact International Rectifier, please visit http://www.irf.com/whoto-call/